

# **Thick Film Process Capabilities**

# Equipment

## Screen printing

#### Systems

Custom blended pastes Substrate size - up to 4" x 6"

#### Line width definition

Resistor element geometry down to 0.007" Conductor linewidths to 0.005"

#### Screens

Sizes up to 8" x 12"

### Firing

Computer controlled belt furnaces

#### Trimming

- Computer controlled abrasive trimmers
- Trim tolerances to 0.1%
- $\clubsuit$  Values from 20 m $\Omega$  to 100 G $\Omega$

#### Separation

- Diamond saw dicing and separation
- Laser machining available

# Die handling and sorting

- Automatic test and ink marking system
- Automatic and semiautomatic tape to waffle pack die pickers
- Tape and reel
- Wave soldering system
- Automatic end metallization system

## QA Systems

- IOO% Visual per MIL-STD-883, Method 2032
- IOO% DC resistance per MIL-STD-202
- Complete MIL-PRF-55342 testing capabilities
- Element evaluation per MIL-PRF-38534, class H and K
- SPC process monitoring
- Cross sectional analysis
- Surface mount reflow soldering
- Customer selected

### **Engineering systems**

- Autocad design, file formats handled include DXF & IGES.
- Comprehensive design review and testing